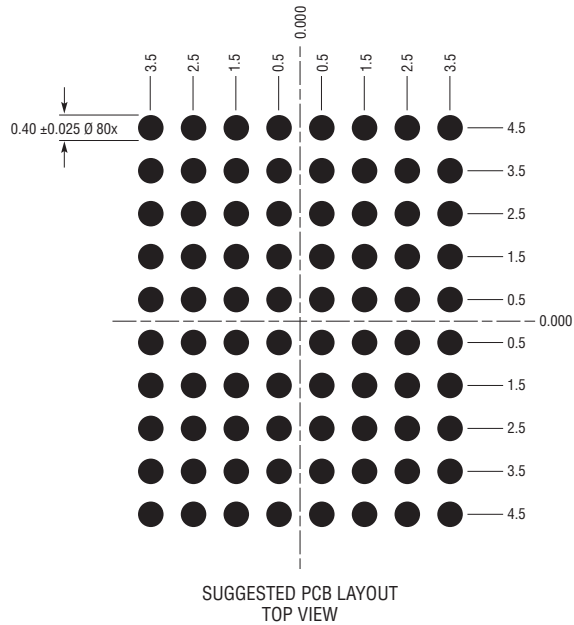
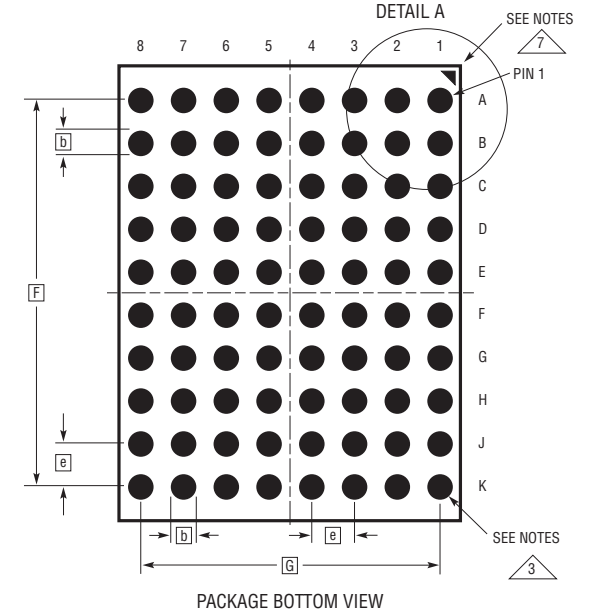
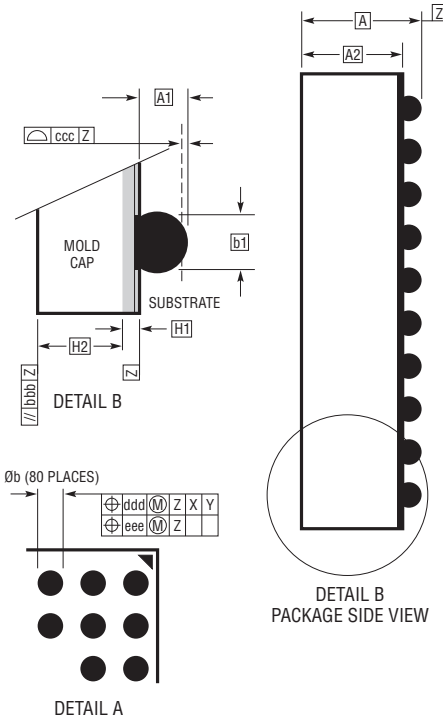
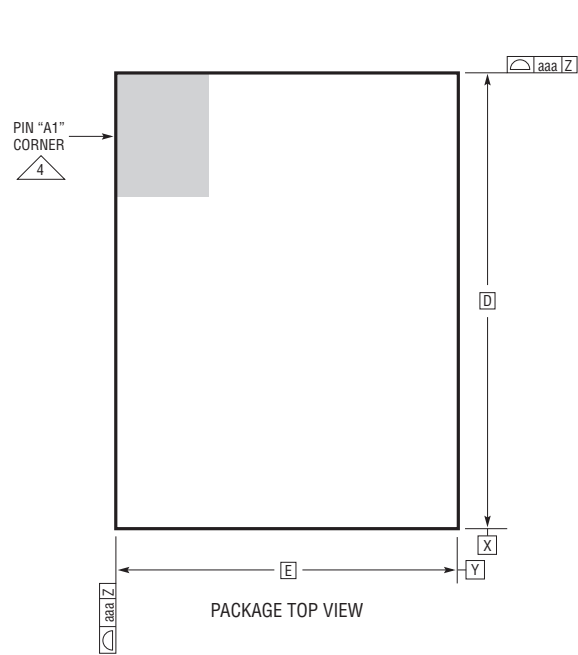


BGA Package
80-Lead (11.25mm × 9mm × 2.22mm)
 (Reference LTC DWG # 05-08-1979 Rev 0)



DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	2.07	2.22	2.37	
A1	0.35	0.40	0.45	
A2	1.72	1.82	1.92	
b	0.45	0.50	0.55	
b1	0.35	0.40	0.45	
D	11.25			
E	9.00			
e	1.00			
F	9.00			
G	7.00			
H1	0.27	0.32	0.37	
H2	1.45	1.50	1.55	
aaa			0.15	
bbb			0.10	
ccc			0.20	
ddd			0.30	
eee			0.15	

TOTAL NUMBER OF BALLS: 80

NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994

2. ALL DIMENSIONS ARE IN MILLIMETERS

3 BALL DESIGNATION PER JESD MS-028 AND JEP95

4 DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE

5. PRIMARY DATUM -Z- IS SEATING PLANE

6. SOLDER BALL COMPOSITION IS 96.5% Sn/3.0% Ag/0.5% Cu

7 PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG μModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY

